

CYLINDRICAL GENERAL PURPOSE SURFACE MOUNT POWER RESISTOR METAL GLAZE™

ISO-9001
Registered



MM SERIES

- Up to 2 watts
- 0.1 ohm to 2.2 megohm range
- Up to 1000 volts
- 150°C maximum operating temperature

Metal Glaze™ thick film
element fired at 1000°C
to solid ceramic substrate



High temperature
dielectric coating

60/40 Solder over nickel barrier

MM SPECIFICATIONS:

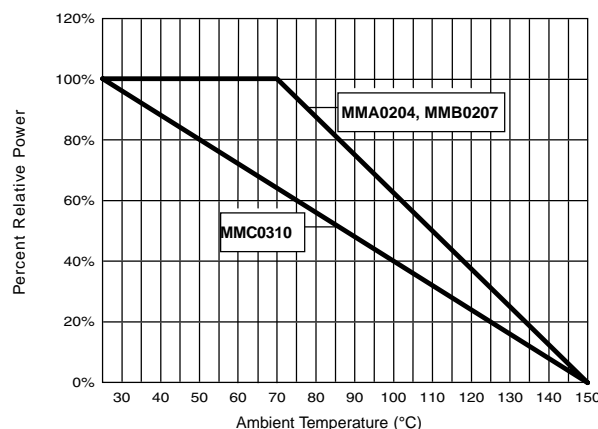
| Size Code | IRC Type | Maximum Power Rating | Working Voltage ¹ | Maximum Voltage | Resistance Range (ohms) ² | Tolerance (±%) ² | TCR (ppm/°C) ² | Product Category |
|-----------|----------|---------------------------|------------------------------|-----------------|--------------------------------------|-----------------------------|---------------------------|-----------------------|
| B | MMA0204 | 1/4W @ 70°C | 200 | 400 | 0.1 to 0.99 1.0 to 1.0 M | 1 1 | 100 50 | Low Range Standard |
| F | MMB0207 | 1W @ 70°C | 350 | 700 | 0.1 to 0.99 1.0 to 2.21M | 1 1 | 100 50 | Low Range Standard |
| H | MMC0310 | 2W @ 25°C 1.33W @ 70°C | 500 | 1000 | 0.2 to 0.99 1.0 to 2.21M | 1 1 | 100 50 | Low Range Standard |

¹Not to exceed $\sqrt{P \times R}$ ²Consult factory for tighter TCR, tolerance, or resistance values. E96 standard EIA Decade Values preferred. E196 and E24 Decade Values available.

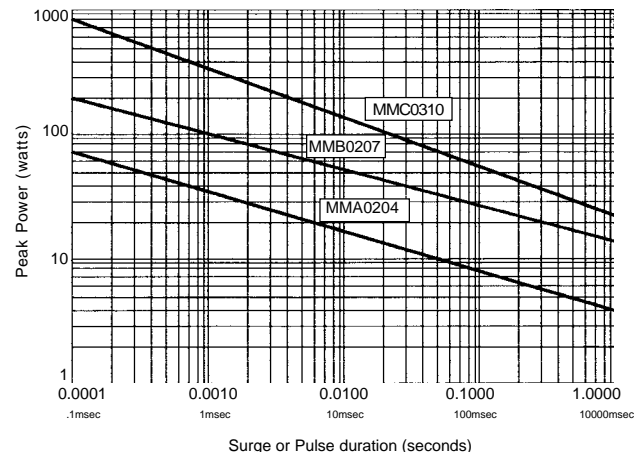
MM PERFORMANCE CHARACTERISTICS:

| Characteristics | Maximum Change | Test Method |
|--------------------------------|--|--|
| Temperature Coefficient | As specified | MIL-R-55342E Par 4.7.9 (-55°C +125°C) |
| Thermal Shock | ±0.5% +0.01 ohm | MIL-R-55342E Par 4.7.3 (-65°C +150°C, 5 cycles) |
| Low Temperature Operation | ±0.25% +0.01 ohm | MIL-R-55342E Par 4.7.4 (-65°C @ working voltage) |
| Short Time Overload | ±1% +0.01 ohm | MIL-R-55342E Par 4.7.5 (2.5 x $\sqrt{P \times R}$ for 5 seconds) |
| High Temperature Exposure | ±0.5% +0.01 ohm | MIL-R-55342E Par 4.7.6 (+150°C for 100 hours) |
| Resistance to Bonding Exposure | ±0.25% 0.01 ohm | MIL-R-55342E Par 4.7.7 (Reflow soldered to board at 260°C for 10 seconds) |
| Solderability | 95% minimum coverage | MIL-STD-202, Method 208 (245°C for 5 seconds) |
| Moisture Resistance | ±0.5% +0.01 ohm | MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours) |
| Life Test | 1% +0.01 ohm | MIL-R-55342E Par 4.7.10 (2000 hour at 70°C intermittent) |
| Terminal Adhesion Strength | ±1% +0.01 ohm no mechanical damage | 1200 gram push from underside of mounted chip for 60 seconds |
| Resistance to Board Bending | ±1% + 0.01 ohm no mechanical damage | Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds |

MM POWER DERATING CURVE:



MM REPETITIVE SURGE CURVE:



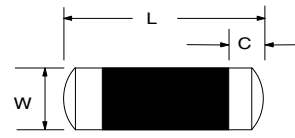



Note: Use for repetitive pulses where the average power dissipation is not to exceed the component rating at 70°C. Surge handling capacity for low-repetitive surges may be significantly greater than shown above. Contact factory for recommendations.

WIREWOUND AND FILM TECHNOLOGIES DIVISION

736 Greenway Road • Boone, North Carolina 28607-1860 • Tel: 828-264-8861 • Fax: 828-264-8866 • www.irctt.com

MM FAMILY STANDARD SIZES, SOLDER PADS AND PACKAGING:

DIMENSIONS (mm and (inches)):

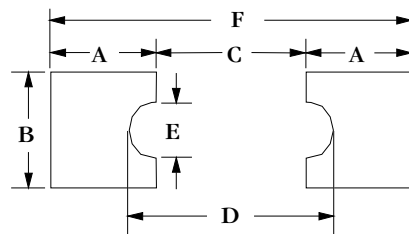
| Size Code | Actual Size |  | | |
|-----------|---|--|----------------------------|---|
| | | L | W | C* |
| B |  | 3.25±0.18 (0.128±0.007) | 1.45±0.15 (0.057±0.006) | 0.51+0.50/-0.38 (0.020+0.020/-0.015) |
| F |  | 6.38±0.25 (0.251±0.010) | 2.01±0.15 (0.079±0.006) | 1.02±0.50 (0.040±0.020) |
| H |  | 9.32±0.25 (0.367±0.010) | 2.67±0.15 (0.105±0.006) | 1.27±0.50 (0.050±0.020) |

*C dimension is average termination width.

RECOMMENDED SOLDER PAD DIMENSIONS (REFLOW):

To ensure excellent solderability performance, IRC recommends the following pad design. This design will provide a large repeatable solder fillet to the MM resistor on reflow processes and will provide maximum heat transfer to the PC board in high power applications. By placing the MM on the solder paste while the paste is in the "tacky" state, the MM will be held in position until solder reflow begins. The pad design then uses the surface tension of the molten solder to pull the component to the center of the solder pad. The placement of a via rising above the board level directly beneath the MM is not recommended.

| Size Code | Dimensions (mm and (inches)) | | | | | |
|-----------|------------------------------|-----------------|-----------------|-----------------|-----------------|------------------|
| | A | B | C | D | E | F |
| B | 1.93 (0.076) | 2.36 (0.093) | 1.47 (0.058) | 2.49 (0.098) | 0.81 (0.032) | 5.36 (0.211) |
| F | 3.07 (0.121) | 3.20 (0.126) | 3.23 (0.127) | 4.65 (0.183) | 1.02 (0.040) | 9.37 (0.369) |
| H | 4.32 (0.170) | 4.06 (0.160) | 5.41 (0.213) | 6.93 (0.273) | 1.12 (0.044) | 14.05 (0.553) |



STANDARD REEL PACKAGING PER EIA-481:

| Size Code | Reel Diameter* | Quantity Per Reel | Carrier Tape Width | Component Pitch |
|-----------|----------------|-------------------|--------------------|-----------------|
| B | 7" | 2,500 max. | 8mm | 4mm |
| | 13" | 10,000 max. | | |
| F | 7" | 1,500 max. | 12mm | 4mm |
| | 13" | 5,000 max. | | |
| H | 13" | 1,500 max. | 24mm | 4mm |

* The 13" reel is considered standard and will be supplied unless otherwise specified.

HOW TO ORDER:

Sample Part No.

MMA0204 - 50 - 2203 - F - 13

IRC Type

(MMA0204, MMB0207, MMC0310)

Temperature Coefficient

(50 or 100)

Resistance Value

(100 ohms and greater - First 3 significant figures plus 4th digit multiplier)

Example: 100 ohms = 1000, 1000 ohms = 1001, 150,000 ohms = 1503

(Less than 100 ohms - "R" is used to designate decimal)

Example: 51 ohms = 51R0, 1 ohm = 1R00, 0.25 ohm = R250

Tolerance

(F = 1.0%)

Packaging Code*

(BLK = Bulk, 7=7" Reel, 13=13" Reel)